

# APPLICATION DATA SHEET

Electronic Version v14

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<b>Title of Invention</b>	[HIGH DENSITY SEMICONDUCTOR PACKAGE]
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 Application Type : | regular, utility | Attorney Docket Number : | 10041-US-PA |

Correspondence address:

Customer Number: 31561



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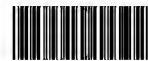
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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.